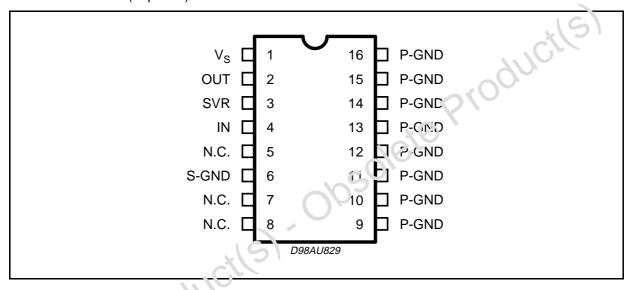
ABSOLUTE MAXIMUM RATINGS

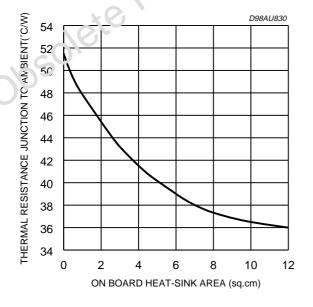
Symbol	Parameter	Value	Unit
Vs	Operating Supply Voltage	18	V
Ιο	Output Put Peak Current	1.5	Α
T _{op}	Operating Temperature Range	0 to 70	°C
Tj	Junction Temperature	150	°C
T _{sta}	Storage Temperature Range	-40 to 125	°C

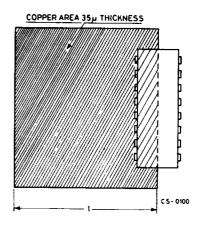
PIN CONNECTION (Top view)



Rth with "on Board" Square i !sat Sink vs. Copper Area

Example of heatsink using PC board copper





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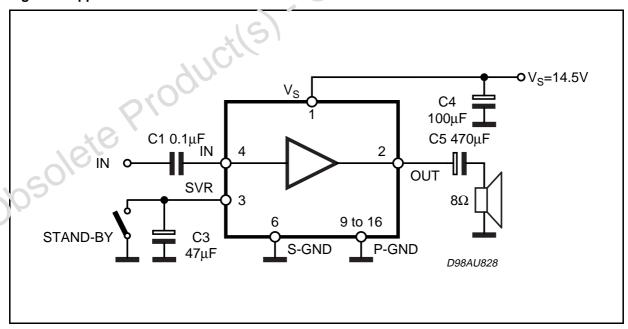
THERMAL DATA

Symbol	Parameter		Unit
R _{th j-amb}	Thermal Resistance Junction to ambient	70	°C/W
R _{th j-case}	Thermal Resistance Junction to case	15	°C/W

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}C$; $V_{S} = 14.5V$; $R_{L} = 8\Omega$; f = 1KHz; unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
Vs	Supply Voltage Range		5		18	V
Is	Quiescent Current			23	35	mA
I _{sb}	Stand-By Current	Pin 3 shorted to GND			0.3	n A
Vo	Quiescent Output Voltage			7.5		V
A _V	Voltage Gain		31	1.1	્ર3	dB
R _{IN}	Input Impedance		50	OC		ΚΩ
Po	Output Power	THD = 10%	27	3		W
THD	Distortion	$P_O = 1W$		0.1	0.3	%
SVR	Supply Voltage Rejection	V _{ripple} = 150mVrms; F _{ripple} = 1KHz		50		dB
Eı	Input Noise Voltage	Rg = 10KΩ; BW = 20Hz to 25KHz		5	10	μV
V _{sb}	Stand-By Enable Voltage	60.			1	V

Figure 1. Application Circuit



APPLICATION HINTS:

For 14.5V supply and 8Ω speaker application, its maximum power dissipation is about 1.8W.

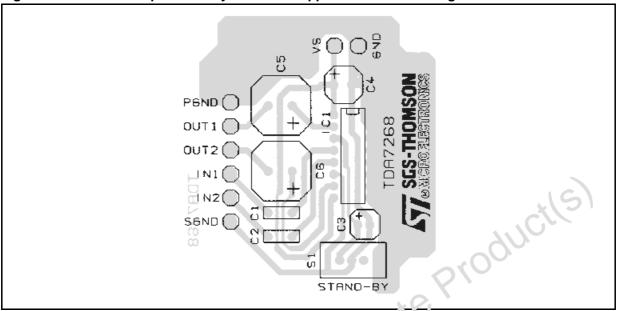
Assumming that max ambient temperature is 70°C, the required thermal resistance of the device mounted on the PCB with a dissipating area

must be equal to: (150 - 70)/1.8 = 44.4°C/W.

Junction to pin thermal resistance of the package is about 15°C/W. That means external heat sink of about 30°C/W is required.

Cu ground plane of PCB can be used as heat dissipating means.

Figure 2. PCB And Components Layout Of The Application Circuit of Figure 1



Components C2 and C6 must be ignored.

Figure 3. Distortion vs Output Power

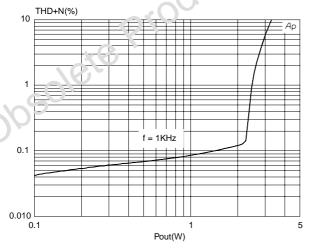
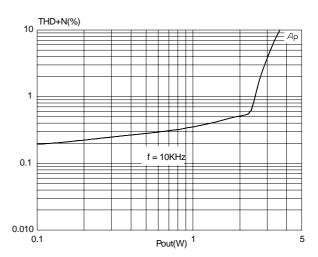


Figure 4. Distortion vs Output Power



Remark: all the characterization curves refer to the electrical test conditions.

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Figure 5. Distortion vs Output Power

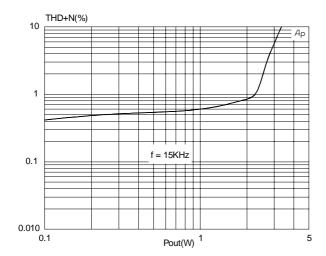


Figure 6. Output Power vs Supply Voltage

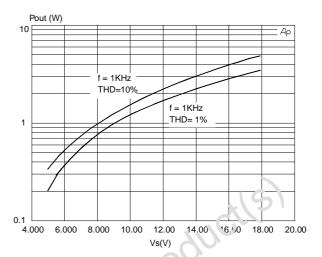


Figure 7. Distortion vs Frequency

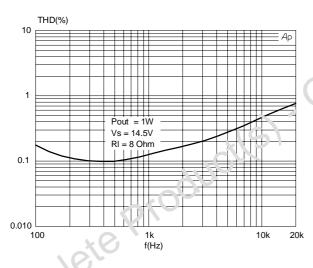


Figure 8. Quiescent current vs Supply Voltage

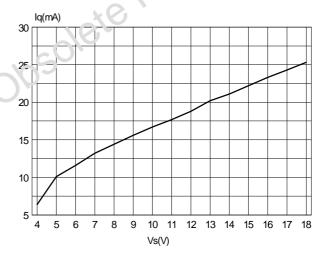
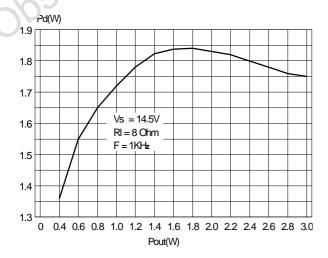


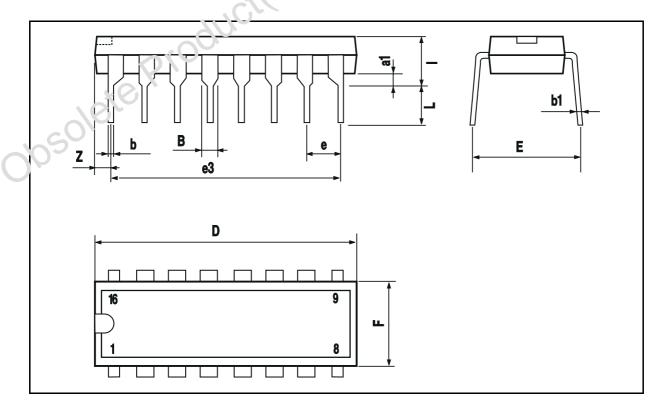
Figure 9 Power dissipation vs Output Power



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POWERDIP 8+8 PACKAGE MECHANICAL DATA

DIM.	mm		inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
В	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
Е		8.5			0.335	Cr
е		2.54			(1.10)	
e3		17.78			0.700	
F			7.1	10th		0.280
I			5.1	0/0		0.201
L		3.3	Up.		0.130	
Z			1.27			0.050



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